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ORIGINALLY FILED

ney Docket No. 23537.90

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application:

Serial No.: 09/806,252
Filed: March 27, 2001

RECEIVED

AUG 06 2002

Technology Center 2600

July 24, 2002

Hon. Commissioner of Patents and Trademarks
Washington D.C. 20231

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